

## SMK1625D2

**Advanced N-Ch Power MOSFET** 

# DC-DC CONVERTER APPLICATION HIGH VOLTAGE SWITCHING APPLICATIONS

#### **Features**

• High Voltage: BV<sub>DSS</sub>=250V (Min.)

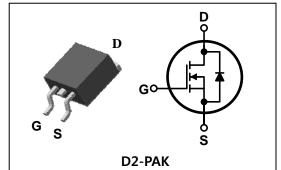
• Low  $C_{rss}$ :  $C_{rss}$ =49pF (Typ.)

• Low gate charge :  $Q_g$ =22nC (Typ.) • Low  $R_{DS(on)}$  :  $R_{DS(on)}$ =0.27 $\Omega$  (Max.)

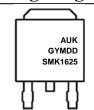
### **Ordering Information**

Type No.	Marking	Package Code		
SMK1625D2	SMK1625	D2-PAK		

#### **PIN Connection**



### **Marking Diagram**



Column 1 : Manufacturer

Column 2: Production Information

e.g.) GYMDD

-. G : Factory management code

-. YMDD: Date Code (year, month, date)

Column 3: Device Code

#### **Absolute maximum ratings** (T<sub>C</sub>=25°C unless otherwise noted)

Characteristic		Symbol		Rating	Unit
Drain-source voltage		$V_{DSS}$		250	V
Gate-source voltage			$V_{GSS}$	±30	V
Drain current (DC) *			(T <sub>C</sub> =25°C)	16	Α
Drain current (DC) *		$I_{D}$	(T <sub>C</sub> =100°C)	7.2	Α
Drain current (Pulsed) *			${ m I}_{\sf DM}$	64	Α
Drain power dissipation *			$P_D$	130	W
Avalanche current (Single)	2		$I_{AS}$	16	Α
Single pulsed avalanche energy	2		$E_{AS}$	480	mJ
Avalanche current (Repetitive)	①		${ m I}_{\sf AR}$	16	Α
Repetitive avalanche energy	①	E <sub>AR</sub>		13.9	mJ
Junction temperature		T <sub>J</sub>		150	°C
Storage temperature range	·	T <sub>stg</sub>		-55~150	C

<sup>\*</sup> Limited by maximum junction temperature

Cha	racteristic	Symbol	Typ.	Max.	Unit
Thermal	Junction-case	R <sub>th(J-C)</sub>	-	0.96	oC/M
resistance	Junction-ambient	R <sub>th(J-A)</sub>	-	62.5	°C/W

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### **Electrical Characteristics** (T<sub>C</sub>=25°C unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Drain-source breakdown voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250uA, V <sub>GS</sub> =0	250	ı	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250uA$ , $V_{DS}=V_{GS}$	2.0	ı	4.0	V
Drain-source cut-off current	$I_{DSS}$	V <sub>DS</sub> =250V, V <sub>GS</sub> =0V	-	ı	1	uA
Gate leakage current	$I_{GSS}$	V <sub>DS</sub> =0V, V <sub>GS</sub> =±30V	-	-	±100	nA
Drain-source on-resistance 4	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =8.0A	-	0.22	0.27	Ω
Forward transfer conductance 4	g <sub>fs</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =8.0A	-	10.5	-	S
Input capacitance	Ciss	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V	-	968	1275	
Output capacitance	Coss	f=1MHz	-	204	278	pF
Reverse transfer capacitance	Crss		-	49	64	
Turn-on delay time	t <sub>d(on)</sub>		-	15	-	
Rise time	t <sub>r</sub>	$V_{DD} = 125V, I_{D} = 16A$	-	130	-	nc
Turn-off delay time	t <sub>d(off)</sub>	$R_G = 25\Omega$	-	135	-	ns
Fall time	t <sub>f</sub>		-	105	-	
Total gate charge	$Q_g$	V <sub>DS</sub> =200V, V <sub>GS</sub> =10V	-	22	28	
Gate-source charge	$Q_{gs}$	I <sub>D</sub> =16A	-	7.1	-	nC
Gate-drain charge	$Q_{gd}$	34	-	5.9	-	

### $\underline{\textbf{Source-Drain Diode Ratings and Characteristics}} \ (\textbf{T}_{\text{C}} = 25^{\circ} \textbf{C} \ \textbf{unless otherwise noted})$

Characteristic		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current		$I_{S}$	Integral reverse diode	-	ı	16	^
Source current (Pulsed)	1	$I_{SM}$	in the MOSFET	-	-	64	Α
Forward voltage	4	$V_{SD}$	V <sub>GS</sub> =0V, I <sub>S</sub> =16A	-	-	1.4	V
Reverse recovery time		t <sub>rr</sub>	I <sub>S</sub> =16A, V <sub>GS</sub> =0	-	208	-	ns
Reverse recovery charge		$Q_{rr}$	dI <sub>F</sub> /dt=100A/us	-	1.63	-	uC

#### Note;

① Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

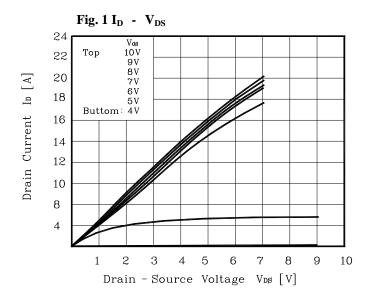
② L=3.0mH,  $I_{AS}$ =16A,  $V_{DD}$ =50V,  $R_{G}$ =25 $\Omega$ 

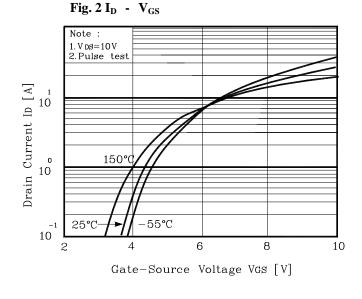
③ Pulse Test: Pulse Width≤ 300us, Duty cycle≤ 2%

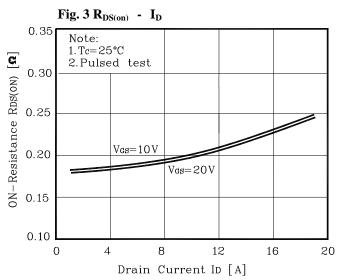
4 Essentially independent of operating temperature

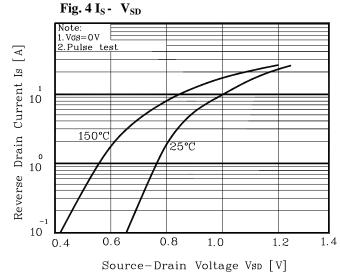
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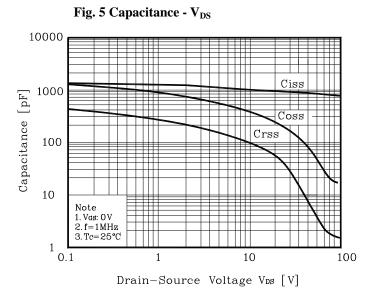
### **Electrical Characteristic Curves**

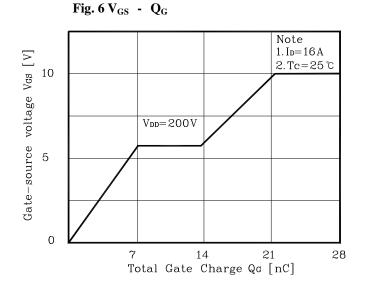












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Fig. 7  $V_{DSS}\,\,$  -  $\,\,T_{J}$ 

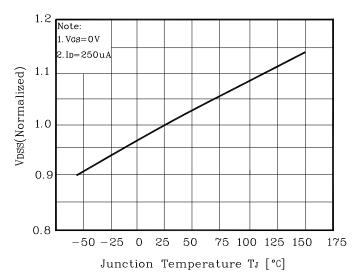


Fig. 9  $I_D - T_C$ 

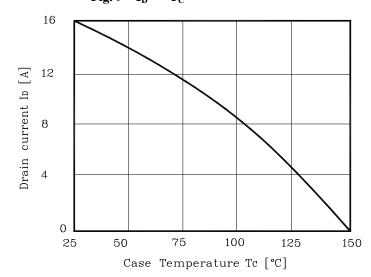


Fig. 8  $R_{DS(on)}\,$  -  $\,T_{J}\,$ 

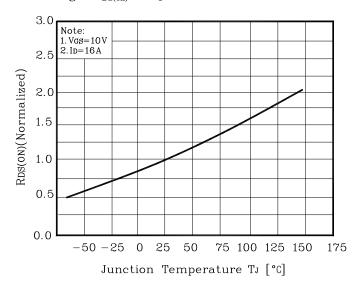


Fig. 10 Safe Operating Area

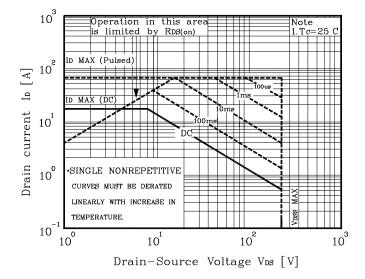


Fig. 11 Gate Charge Test Circuit & Waveform

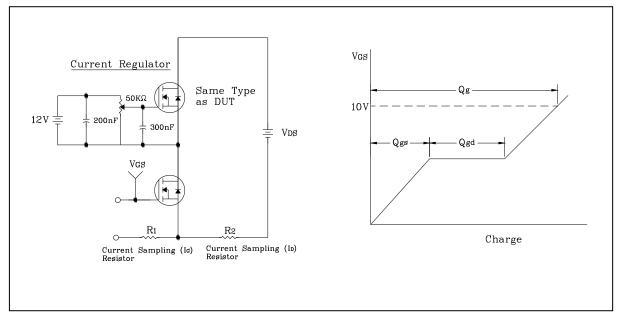


Fig. 12 Resistive Switching Test Circuit & Waveform

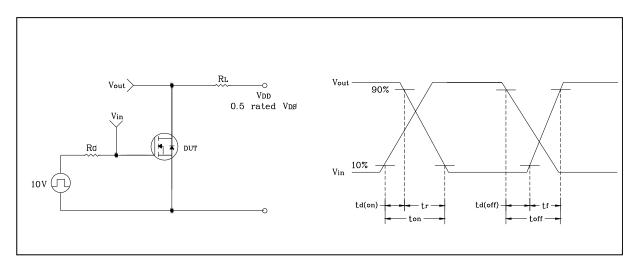


Fig. 13  $E_{AS}$  Test Circuit & Waveform

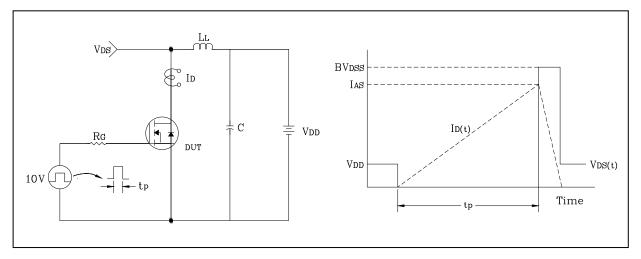
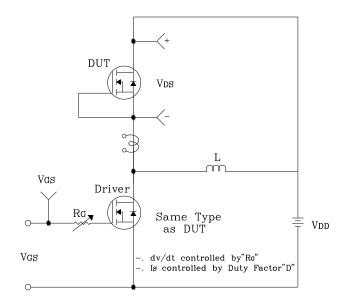
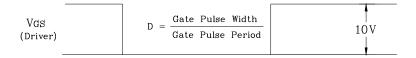
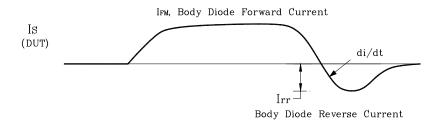
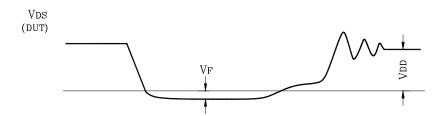


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform





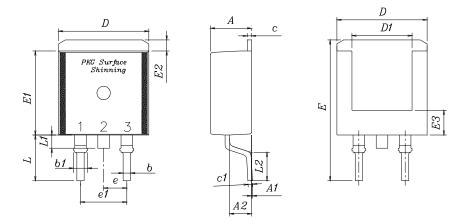




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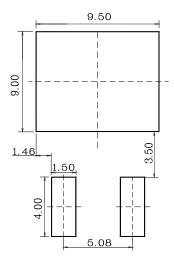
### **Outline Dimension**

unit: mm



	ľ	NOTE			
SYMB0L	MINIMUM	NOMINAL	MAXIMUM	NOTE	
Α	4.35	4.50	4.65		
A1	_	-	0.15		
A2	2.20	2.40	2.60		
b	0.70	0.80	0.90		
b1	1.17	1.27	1.37		
С	0.40	0.50	0.60		
c1	0.40	0.50	0.60		
D	9.80	10.00	10.20		
D1	6.40	6.60	6.80		
Ε	15.00	15.40	15.80		
E1	9.05	9.20	9.35		
E2	1.00	1.20	1.40		
E3	2.50	2.70	2.90		
е	2.34	2.54	2.74		
e 1	4.88	5.08	5.28		
L	4.60	5.00	5.40		
<u>L</u> 1	1.40	1.45	1.50		
L2	2.50	_	_		

### **\*\* Recommended Land Pattern** [unit: mm]



### SMK1625D2

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